

股票代號：2404

漢唐集成股份有限公司 法人說明會

**United Integrated Services Co.
Investor Conference**

2018/11/20



uis

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Agenda

- **漢唐集成公司簡介 (About UIS)**
- **營運概況說明 (Operation)**
- **財務狀況說明 (Financials)**
- **業務展望 (Future Prospects)**
- **Q & A**

關於漢唐集成

漢唐集成成立於1982年，為一以「全面性整合服務」方式，專業提供高科技產業建廠之系統集成服務公司；主要業務範圍包括技術顧問服務、高科技整廠集成專案及電腦、控制、無塵室、機電、電信系統之專案業務。

漢唐集成的工程系統完備，服務更講求以提供「整體解決方案」之方式，一次滿足客戶需求。針對高科技事業建廠所需之建築工程系統、無塵室系統、機械系統、電氣系統、配管系統、製程支援系統、儀錶及控制系統、通訊系統、生命安全系統、門禁及安全管理系統、空間規劃管理、大宗及特殊氣體系統、超純水（UPW）及再生系統、超純水回收系統、廢水處理與製程化學品輸送，及二次配管路工程等系統，均囊括在漢唐集成的服務範圍內。

漢唐集成並就以上各項系統提供從規劃、設計、施工、試車、移交、保固到維修，及營建之監督及管理的服務，同時將以上各項系統工程加以整合，達成介面統一，使客戶完全無需擔憂各個不同系統之間的整合問題；目前全國亦唯有漢唐集成真正有此能力，可將各種高技術系統工程加以集成。

About UIS

United Integrated Services Co., Ltd is a multidisciplinary engineering and construction company that is capable of overall systems coordination. We provide fully integrated design/build services to our clients in the high technology industry for their manufacturing facility needs.

Our scope of services include engineering consulting, high-tech factory planning and delivery in which clean-room systems, HVAC, electrical systems, instrumentation and control, process utilities, telecommunication systems and tool hook-up are all vital parts in need of total coordination. Our value added integrated turn-key services not only provide continuity from planning, design, procurement, construction, tool hook-up and start-up/commissioning but also go beyond after service by assisting our clients in facility operation and maintenance.

In short, we strive to be a one-stop shop to satisfy our clients' every facility needs.

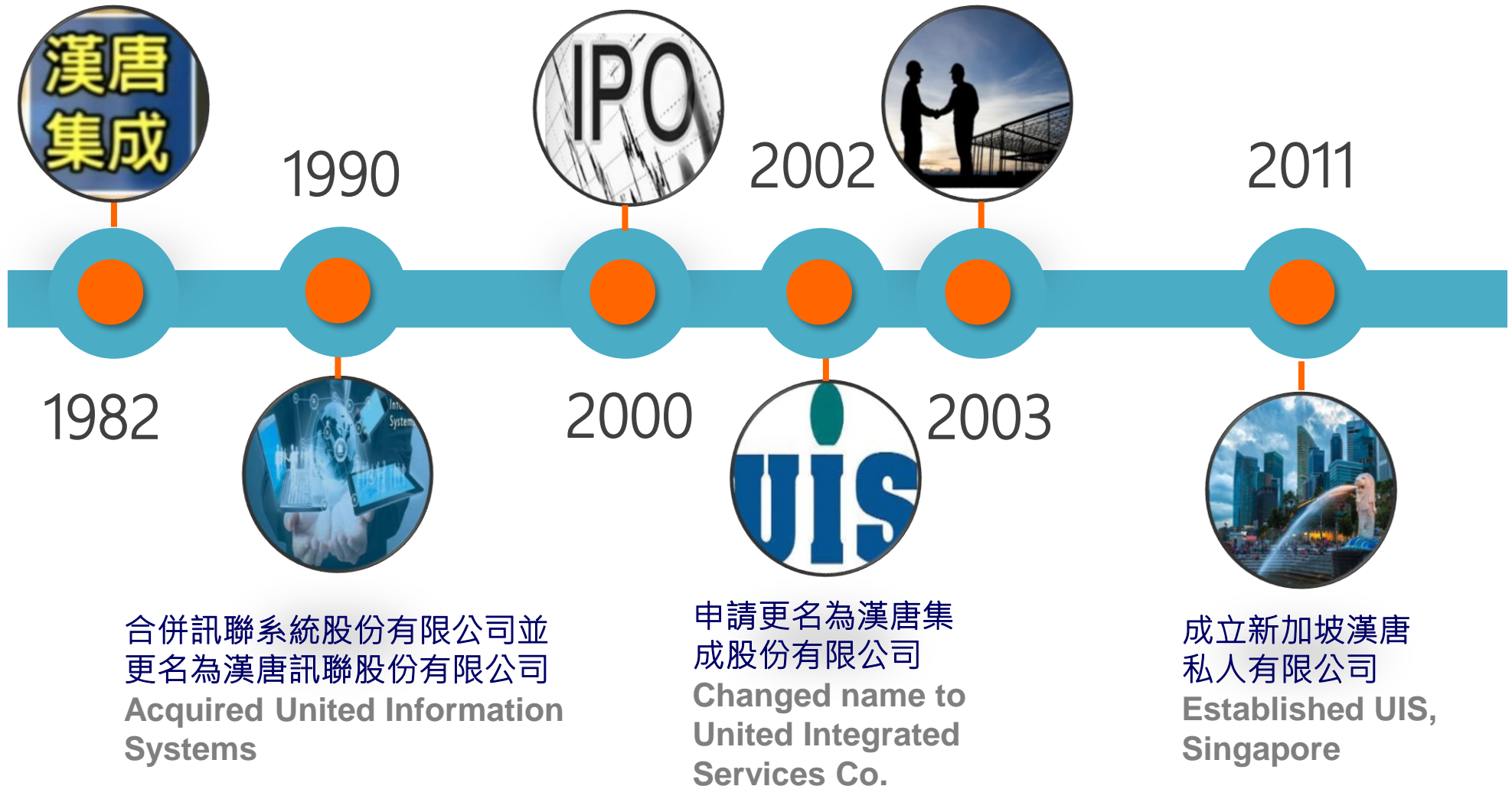
UIS歷史沿革

About UIS

漢唐科技工程有
限公司成立
Company
Established

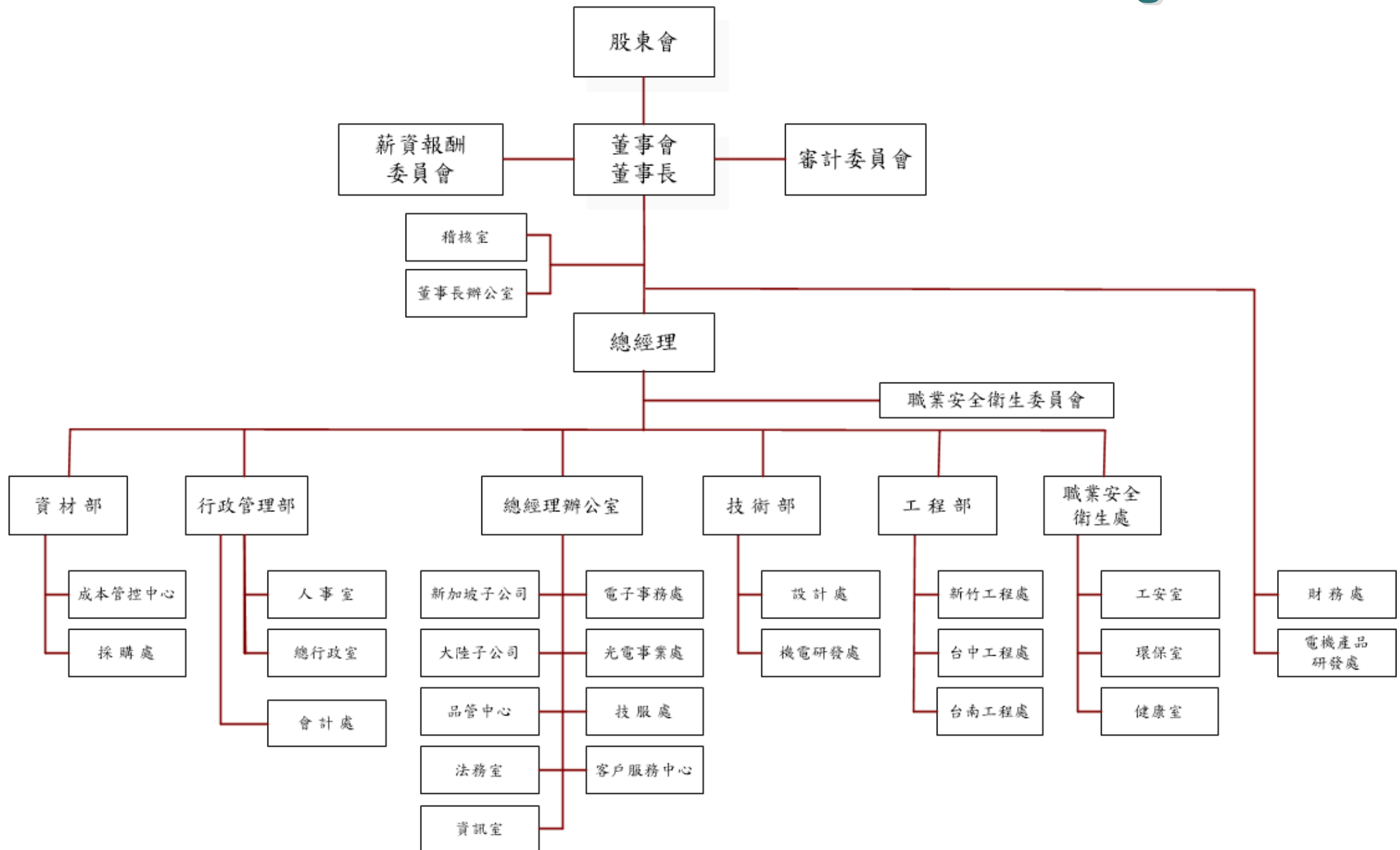
申請掛牌上市(股
票代號 2404)
IPO

成立江西漢唐系統
集成有限公司
Established UIS,
Jiang Xi



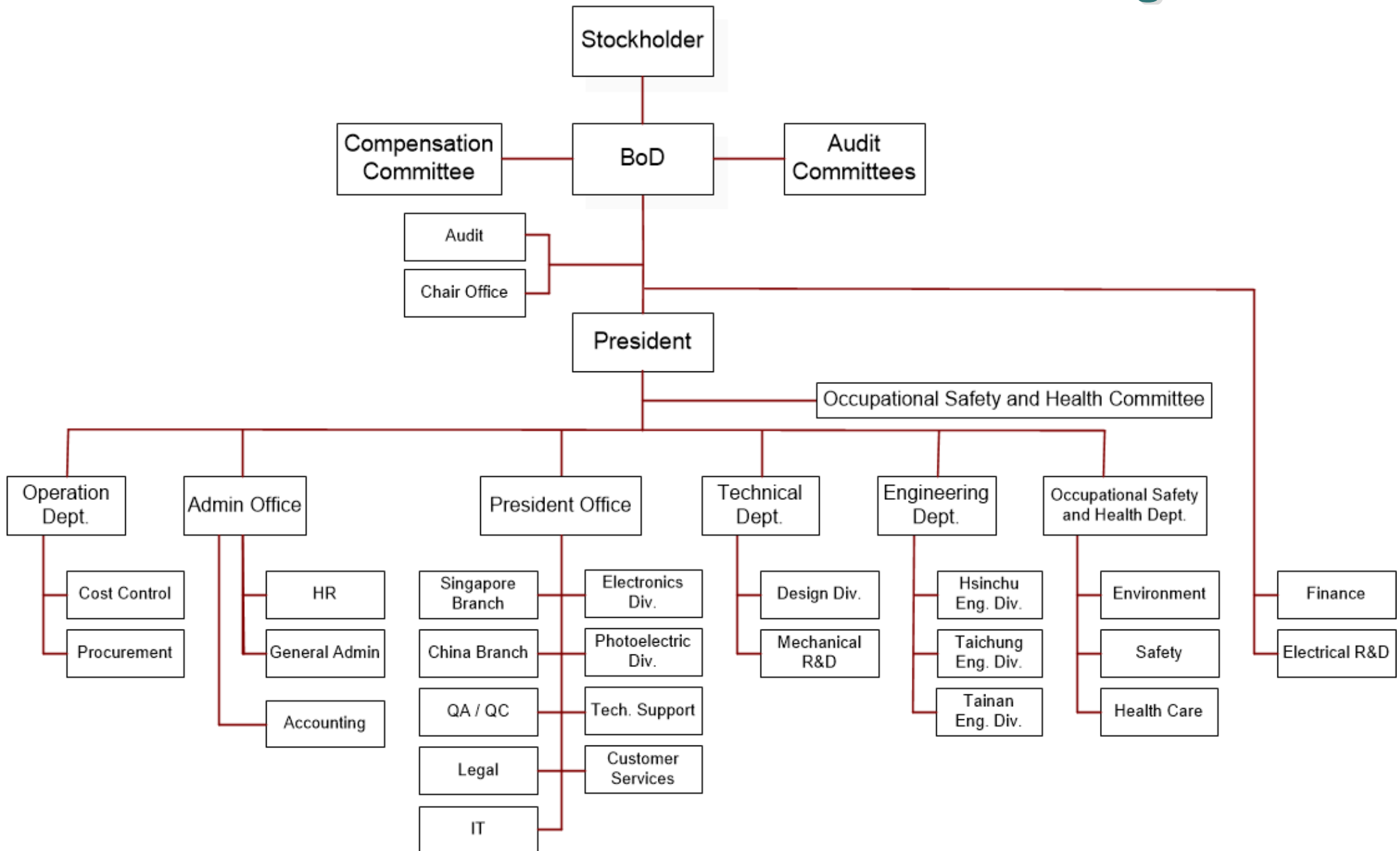
UIS公司組織表

Organization

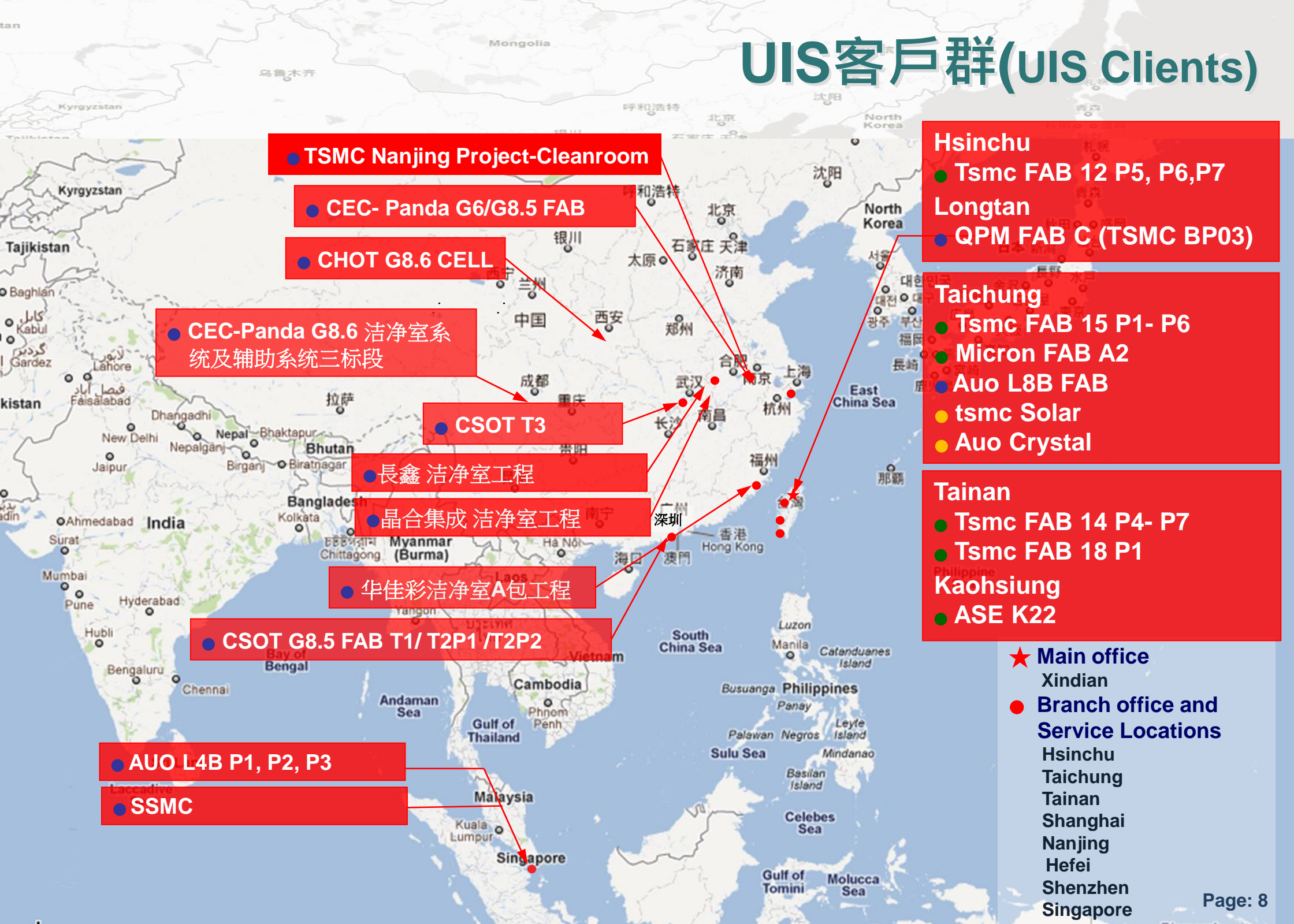


UIS公司組織表

Organization



UIS客戶群(UIS Clients)



● TSMC Nanjing Project-Cleanroom

● CEC- Panda G6/G8.5 FAB

● CHOT G8.6 CELL

● CEC-Panda G8.6 洁净室系统及辅助系统三标段

● CSOT T3

● 長鑫 洁净室工程

● 晶合集成 洁净室工程

● 华佳彩洁净室A包工程

● CSOT G8.5 FAB T1/ T2P1 /T2P2

● AUO L4B P1, P2, P3

● SSMC

Hsinchu
 ● Tsmc FAB 12 P5, P6,P7
Longtan
 ● QPM FAB C (TSMC BP03)

Taichung
 ● Tsmc FAB 15 P1- P6
 ● Micron FAB A2
 ● Auo L8B FAB
 ● tsmc Solar
 ● Auo Crystal

Tainan
 ● Tsmc FAB 14 P4- P7
 ● Tsmc FAB 18 P1
Kaohsiung
 ● ASE K22

- ★ Main office
Xindian
- Branch office and Service Locations
Hsinchu
Taichung
Tainan
Shanghai
Nanjing
Hefei
Shenzhen
Singapore

■ 工程承包範圍

Scope of Engineering

- 無塵室工程
Cleanroom
- 機電工程
Mech. / Elec. Engineering
- 水氣化等特殊系統工程
Gas / Chem. / Special
Systems
- 監控系統工程
I&C

■ 服務範圍

Scope of Services

- 工程顧問服務
Consulting
- 工程設計
Design
- 工程施工
Construction
- 工程監造
construction supervision
- 售後服務
After Sale Services

整合服務

System Integration

- **Architectural Systems**
 - ✓ Civil
 - ✓ Landscaping
 - ✓ Finishes
 - ✓ Exterior Wall System
 - ✓ Special Equipment; such as kitchen equipment, loading/unloading, etc.
 - ✓ Interior of general areas
 - ✓ Aesthetic Lighting
- **Structural Systems**
 - ✓ Piling
 - ✓ Foundations
 - ✓ Structural Floors and Walls
 - ✓ Seismic Considerations



- **Wastewater collection and treatment**
- **Bulk gas, specialty gas and clean dry air**
- **Chemical delivery, waste chemical collection, and chemical reclaim**
- **Mechanical System**
- **Electrical System**
- **Plumbing System**
- **Cleanroom System**
 - ✓ Partitions, Floors, and Ceiling
 - ✓ Temperature and Humidity Control
 - ✓ Process Support
 - ✓ Process Exhaust
 - ✓ Contamination Control
 - ✓ Lighting

Taiwan Semiconductor Manufacturing Company, Ltd.

tsmc FAB III

tsmc FAB IV

tsmc FAB VI

tsmc FAB XII P1, P2, P3, P4, P5, P6, P7

tsmc FAB XIV P1, P2, P3, P4, P5, P6, P7

tsmc FAB XV P1, P2, P3, P4, P5, P6, P7

tsmc FAB XVIII P1

tsmc NANJING F16P1

Powerchip Semiconductor Corp.

PSC FAB 8A

PSC FAB P3

PSC FAB P4, P5

Micron Memory Taiwan Co., Ltd.

Micron FAB A1

Micron FAB A2

Winbond Electronics Corp.

Winbond FAB I

Winbond FAB II

Winbond FAB III

Winbond FAB IV

Winbond FAB CTSP, FAB 6C

Macronix International Co., Ltd.

MXIC FAB I

MXIC FAB II

MXIC FAB III

台灣積體電路製造股份有限公司

台積電三廠

台積電四廠

台積電六廠

台積電十二廠 P1, P2, P3, P4, P5, P6, P7

台積電十四廠 P1, P2, P3, P4, P5, P6, P7

台積電十五廠 P1, P2, P3, P4, P5, P6, P7

台積電十八廠 P1

台積電南京廠 F16P1

力晶半導體股份有限公司

力晶 FAB 8A

力晶 FAB P3

力晶 FAB P4, P5

台灣美光記憶體股份有限公司

美光 FAB A1

美光 FAB A2

華邦電子股份有限公司

華邦 FAB I

華邦 FAB II

華邦 FAB III

華邦 FAB IV

華邦 FAB CTSP, FAB 6C

旺宏電子股份有限公司

旺宏 FAB I

旺宏 FAB II

旺宏 FAB III

AU Optronics Corp.

auo FAB L3C
auo FAB L3D (QDI Line I)
auo FAB L4A
auo FAB L5A
auo FAB L5B
auo FAB L5C
auo FAB L5D (QDI Line II)
auo FAB L6A
auo FAB L6B (QDI Line III)
auo FAB L7A, L7B
auo FAB L8A, L8B

Chi Mei Optoelectronics Corp.

CMO FAB III
CMO FAB IV
CMO FAB V
CMO FAB VI
CMO FAB VII
CMO FAB VIII

HannStar Display Corp.

HannSrar FAB I
HannSrar FAB II
HannSrar FAB III
HannSrar FAB IV

Nanjing CEC Panda LCD Technology Co., Ltd.

CEC Panda G6 FAB
CEC Panda G8.5 FAB

CSOT Corporation

CSOT G8.5 FAB(T1)
CSOT G8.5 FAB II(T2)
CSOT LTPS(T3)

Qualcomm Panel Manufacturing Ltd.

QMP FAB C

Century Display (Shenzhen) Co., Ltd CDY Array/CF K1FAB

友達光電股份有限公司

友達 FAB L3C
友達 FAB L3D (QDI Line I)
友達 FAB L4A
友達 FAB L5A
友達 FAB L5B
友達 FAB L5C
友達 FAB L5D (QDI Line II)
友達 FAB L6A
友達 FAB L6B (QDI Line III)
友達 FAB L7A, L7B
友達 FAB L8A, L8B

奇美電子股份有限公司

奇美 FAB 三廠
奇美 FAB 四廠
奇美 FAB 五廠
奇美 FAB 六廠
奇美 FAB 七廠
奇美 FAB 八廠

瀚宇彩晶股份有限公司

瀚宇彩晶 FAB I
瀚宇彩晶 FAB II
瀚宇彩晶 FAB III
瀚宇彩晶 FAB IV

南京中電熊貓液晶顯示科技有限公司

南京中電熊貓6代廠
南京中電熊貓8.5代廠

華星科技有限公司

華星科技8.5代廠(T1廠)
華星科技8.5代廠(T2廠)
華星科技 LTPS(T3廠)

高通液晶顯示器股份有限公司

高通 FAB C

深超光電(深圳)有限公司

CDY Array/CF K1FAB

主要客戶

Solar & Others

Taiwan Semiconductor Manufacturing Company, Ltd

tsmc Solar FAB

AUO Crystal Corp.,

auo Crystal Wuqi

auo Crystal Houli

Darwin Precisions Corporation

Tianma Microelectronics Co., Ltd

Tripod Technology Corporation

BenQ Hospital

Global Advanced Packaging Technology
Limited

Radiant Opto-Electronics Corporation

Shanghai Huahong (Group) Co., Ltd.

Taiwan Polysilicon Corp.

Advanced Semiconductor Engineering Inc

ChipMOS TECHNOLOGIES INC

Xintec Inc

Thailin Semiconductor Corp.

ProMOS Technologies Inc

AGC Display Glass Taiwan Co.,Ltd.

Hermes-Epitek Corp

Chipmore Technology Corporation Limited

TCL Communication Technology Holdings
Limited

BASED SOLAR (JIANGSU) ENERGY HIGH
TECHNOLOGY CO., LTD

Kunshan Guoxian Optoelectronics Co., Ltd.

主要客戶

Solar & Others

台灣積體電路製造股份有限公司

tsmc Solar FAB

友達晶材股份有限公司

auo Crystal 中港廠

auo Crystal 后里廠

Darwin Precisions Corporation

Tianma Microelectronics Co., Ltd

Tripod Technology Corporation

BenQ Hospital

威宇科技封裝測試有限公司

瑞儀光電(南京)有限公司

華虹NEC(上海)有限公司

福聚太陽能股份有限公司

日月光半導體製造股份有限公司

南茂科技股份有限公司

精材科技股份有限公司

泰林科技股份有限公司

茂德科技股份有限公司

旭硝子顯示玻璃股份有限公司

漢民科技股份有限公司

頤中科技(蘇州)有限公司

TCL光電科技(惠州)有限公司

江蘇百世德太陽能高科技有限公司

昆山龍騰光電有限公司

近五年盈餘分配狀況

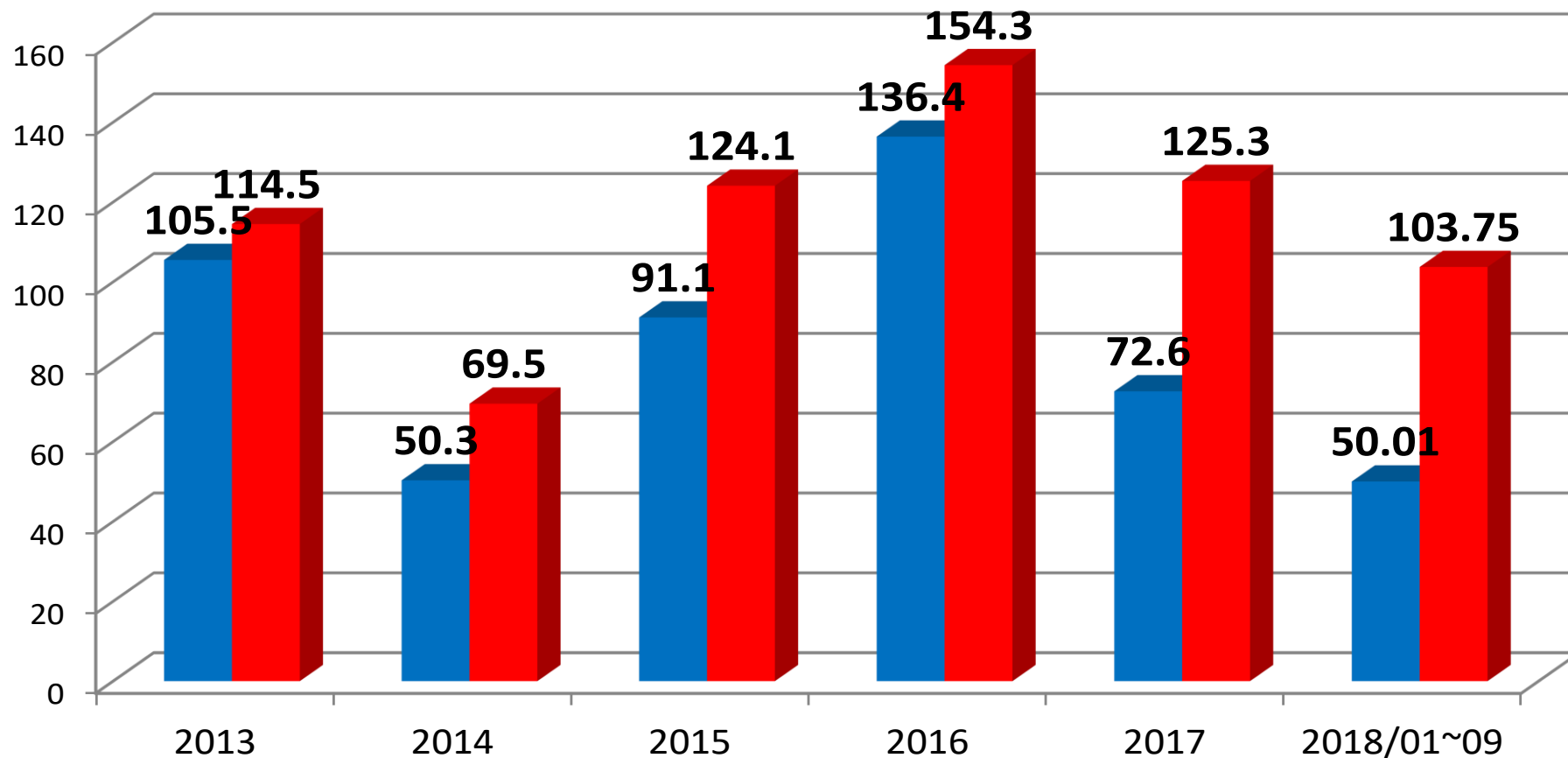
Income Statement

	101年 (2012)	102年 (2013)	103年 (2014)	104年 (2015)	105年 (2016)	106年 (2017)	107年(01~9月) (2018 Jan.~Sep.)
營業收入(千元) Rev.(thousand)	9,163,188	11,445,015	6,949,507	12,418,557	15,426,851	12,525,918	10,374,731
毛利(千元) Gross Profit(thousnad)	1,193,849	1,727,955	1,252,845	1,742,768	2,380,513	2,234,514	1,894,489
毛利率 Gross Profit %	13.03%	15.10%	18.03%	14.03%	15.43%	17.84%	18.26%
本期稅後損益(千元) EAT(thousand)	527,379	1,134,184	771,617	1,280,670	1,585,347	1,341,764	1,486,714
每股盈餘(元) EPS	2.28	4.73	3.14	5.24	6.52	5.10	5.91
現金股利(元) Cash Dividends	1.80	2.40	2.50	4.50	6.00	5.00	
股利發放率 Dividend Payout Ratio	78.95%	50.74%	79.62%	85.88%	92.02%	98.04%	
負債佔資產比率 Debt Asset Ratio	57.85%	53.67%	59.15%	57.68%	60.94%	60.26%	
流動比率 Current Ratio	144.99%	158.61%	138.48%	147.33%	140.48%	144.04%	
純益率 Net Profit Margin	5.76%	9.91%	11.10%	10.31%	10.28%	10.71%	

近五年營收 (Revenue)

單位:億元

Unit:NTD 100 million



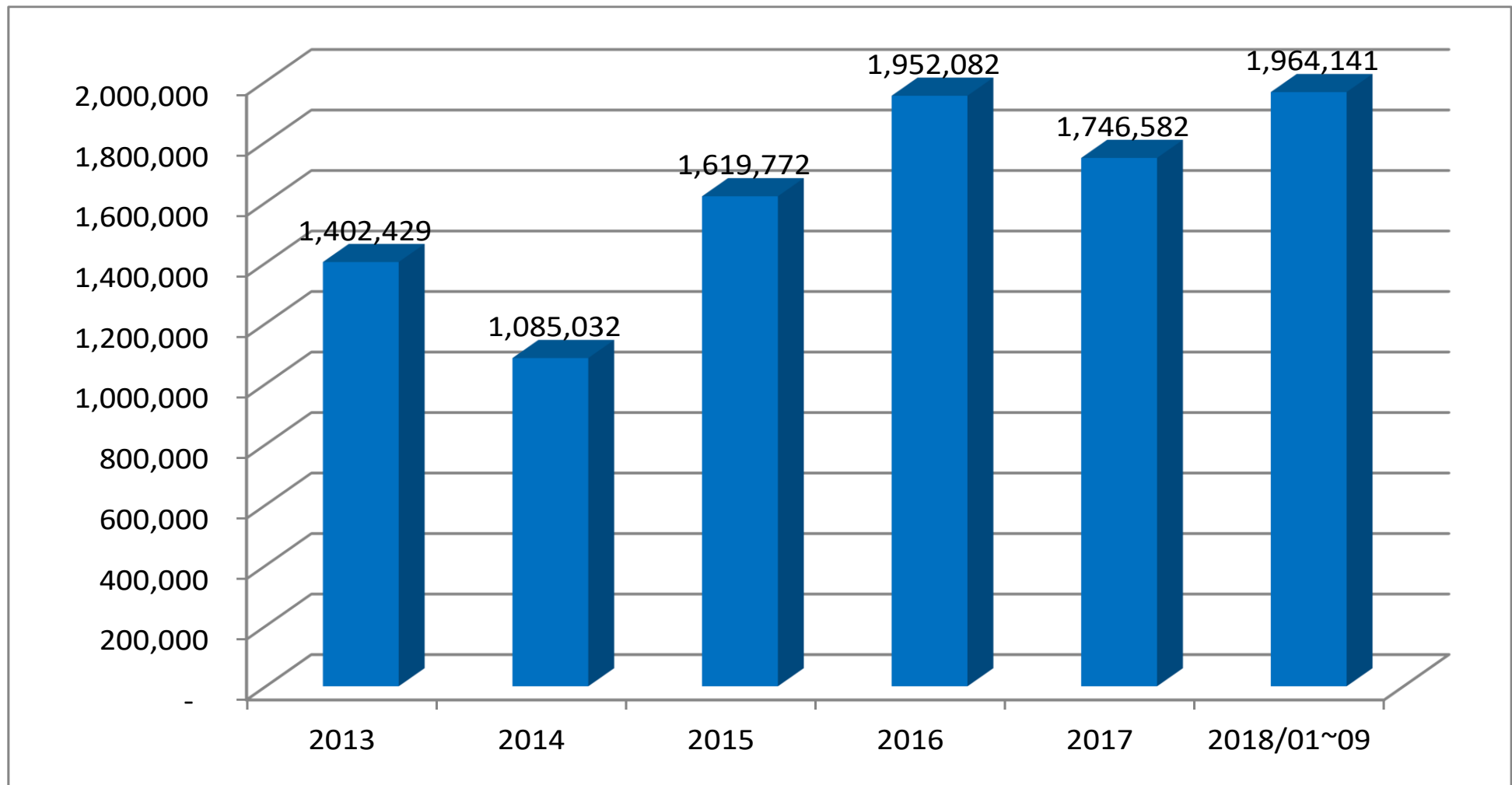
■ 個體營收 Individual

■ 合併營收 Consolidated

近五年稅前淨利 (EBIT)

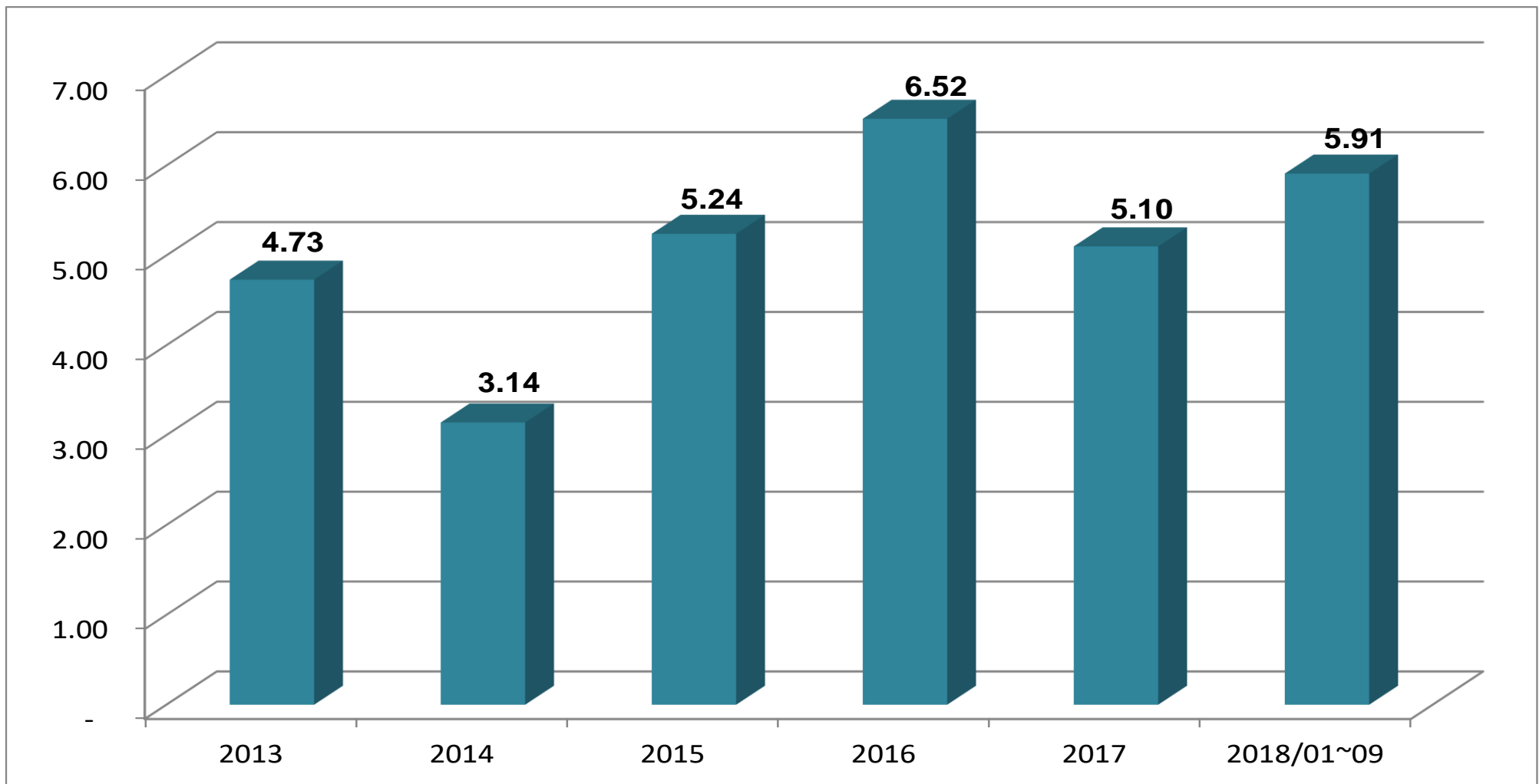
單位:仟元

Unit: NTD thousand



每股盈餘 (EPS)

Unit: NTD



累計接單狀況統計

Business in total

- **107年接單合約金額**
2018 Contract Value **NTD21,906,552千元**
(thousand)
- **107年1月至10月累計營收**
Accumulated Rev. **NTD12,852,016千元**
(from Jan. to Oct.) (thousand)
- **截至107年10已簽約未認列之金額**
Accumulated **NTD24,816,995千元**
Account Receivable
(to Oct.) (thousand)

台灣地區

Taiwan

➤ **107年1月至10月累計營收**

Accumulated Rev.
(from Jan. to Oct.)

NTD6,400,738仟元
(thousand)

➤ **截至107年10已簽約未認列之金額**

Accumulated
Account Receivable
(to Oct.)

NTD17,227,412仟元
(thousand)

大陸地區

China

➤ **107年1月至10月累計營收**

NTD5,192,619千元

Accumulated Rev.
(from Jan. to Oct.)

(thousand)

➤ **截至107年10已簽約未認列之金額**

NTD7,047,581千元

Accumulated
Account Receivable
(to Oct.)

(thousand)

新加坡地區

Singapore

➤ **107年1月至10月累計營收**

NTD1,258,659千元

Accumulated Rev.
(from Jan. to Oct.)

(thousand)

➤ **截至107年10已簽約未認列之金額**

NTD542,002千元

Accumulated
Account Receivable
(to Oct.)

(thousand)

財務狀況說明

Financials

第三季合併資產負債表

2018 Q3 Consolidated Balance Sheet

單位:千元
Unit: thousand

	107/09/30	106/12/31	106/09/30		107/09/30	106/12/31	106/09/30
現金及約當現金 Cash	7,679,375	7,995,750	7,678,728	應付帳款 PA	3,466,232	2,349,819	2,485,122
應收建造合約款 AR	2,088,498	1,695,309	1,651,990	應付建造合約款 Construction Contract Payables		6,557,290	5,641,979
其他流動資產 Others	6,548,344	4,158,855	3,313,383	其他流動負債 Others	8,949,669	707,991	659,139
流動資產合計 Total Current Assets	16,316,217	13,849,914	12,644,101	流動負債合計 Total Current Liabilities	12,415,901	9,615,100	8,786,240
不動產、廠房及設備 PPE	811,970	736,116	740,480	其他非流動負債 Others	413,425	403,111	308,650
其他非流動資產 Others	3,388,183	2,039,541	2,078,994				
非流動資產合計 Total Non-current Assets	4,200,153	2,775,657	2,819,474	負債總計 Total Liabilities	12,829,326	10,018,211	9,094,890
				股東權益總計 Total SE	7,687,044	6,607,360	6,368,685
資產總計 Total Assests	20,516,370	16,625,571	15,463,575	負債及權益總計 Total Liabilities+SE	20,516,370	16,625,571	15,463,575

若本簡報引述的財務資料，與已對外公告的財務報告有不符的情形，以已對外公告的財務報告的內容為主。

If there is any conflict between, or any difference in the financial information quoted in this presentation and the announced financial report, the announced financial report shall prevail

財務狀況說明

Financials

107年第三季合併損益表

2018 Q3 Consolidated Income Statement

單位:千元
Unit: thousand

	107年1月至9月 2018 Jan.~Sep.		106年1月至9月 2017 Jan.~Sep.	
營業收入 Revenue	10,374,731	100%	9,921,141	100%
營業成本 Cost	8,480,242	82%	8,256,231	83%
營業毛利 Gross Profit	1,738,860	18%	1,664,910	17%
營業費用 Operating expenses	582,467	5%	446,012	4%
營業淨利 Operating Income	1,312,022	13%	1,218,898	13%
營業外收入淨額 Net non-operating income	652,119	6%	134,756	1%
稅前淨利 EBIT	1,964,141	19%	1,353,654	14%
所得稅費用 Income Tax	477,427	5%	310,978	3%
本期淨利 Net Income	1,486,714	14%	1,042,676	11%
本期淨利歸屬於母公司 Net Income (Parent company)	1,408,896	13%	971,811	10%
綜合損益屬於母公司 Composite Net Income (Parent Company)	835,578	9%	998,758	10%
基本每股盈餘 EPS	5.91		4.08	
稀釋每股盈餘 Diluted EPS	5.79		3.99	

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■ 大陸地區 (China)

未來大陸地區半導體及面板產業新建工程，仍然非常熱絡。但是否會受中美貿易戰影響尚待觀察。

High demand in the construction of new facilities in semiconductor and FPD industries , but whether it will be affected by the USA and China trade war still to be observed.

■ 台灣地區 (Taiwan)

明年起在台灣有台積電、美光、華邦等都有建廠計劃，景氣仍然熱絡。

Form next year, TSMC, Micron, Winbond , etc., are all planning to build new facilities, expected that the economy is still hot.

Thank You

Q & A